

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	1452	(438/113 or 438/114 or 438/119). ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/12 15:13
S2	199390	protect\$4 with (lid or substrate or wafer or cap)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/12 15:15
S3	2883802	chip or die or ic or integrated adj3 circuit or micro\$device or micro\$1machine or micro adj3 (device or machine) or mems	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/12 16:07
S4	3215596	trench or recess or groove or cavity	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/12 15:18
S5	7351412	singulat\$4 or cut or saw or dice\$1 or dicing or separat\$4 or divid\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/12 17:27
S6	22305	S2 same S4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/12 15:20
S7	6355	S6 and S3 and S5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/12 15:21
S8	754317	S3 same S5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/12 15:21

S9	3530	S6 and S8	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/12 15:21
S10	2496901	encapsulat\$4 or seal\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/12 15:22
S11	2931	S7 and S10	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/12 15:23
S12	919695	packag\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/13 11:57
S13	1206	S11 and S12	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/12 15:23
S14	2900702	S3 or micro\$1electronic or micro adj5 electronic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/12 16:08
S15	118455	hermetic\$6 with seal\$5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/12 16:09
S16	12997	S14 and S15 and S4 and S5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/12 16:10

S17	6029	S16 and S12	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/12 16:10
S18	30949	wafer\$1level or wafer\$1scal\$3 or substrate\$1level or substrate\$1scal\$3 or (wafer or substrate) adj3 (level or scal\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/13 11:56
S19	650	S17 and S18	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/12 16:12
S20	7686551	singulat\$4 or cut or cutting or saw\$3 or dice\$1 or dicing or separat\$4 or divid\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/13 11:57
S21	761	S14 and S15 and S4 and S18 and S20	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/13 11:58
S22	4575277	micro\$1cap\$4 or micro\$1lid\$4 or cap\$4 or lid	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/13 11:56
S23	30994	wafer\$1level or wafer\$1scal\$3 or substrate\$1level or substrate\$1scal\$3 or (wafer or substrate) adj3 (level or scal\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/13 11:56
S24	920586	packag\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/13 11:57

S25	7690912	singulat\$4 or cut or cutting or saw\$3 or dice\$1 or dicing or separat\$4 or divid\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/13 11:57
S26	2885497	chip or die or ic or integrated adj3 circuit or micro\$device or micro\$1machine or micro adj3 (device or machine) or mems	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/13 11:58
S27	3217079	trench or recess or groove or cavity	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/13 11:58
S28	2902416	S26 or micro\$1electronic or micro adj5 electronic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/13 11:58
S29	118532	hermetic\$6 with seal\$5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/13 11:58
S30	30994	wafer\$1level or wafer\$1scal\$3 or substrate\$1level or substrate\$1scal\$3 or (wafer or substrate) adj3 (level or scal\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/13 11:58
S31	7690912	singulat\$4 or cut or cutting or saw\$3 or dice\$1 or dicing or separat\$4 or divid\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/13 11:58
S32	763	S28 and S29 and S27 and S30 and S31	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/13 12:01

S33	5232	S22 and S23 and S24 and S25	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/13 12:02
S34	4581	S33 and S28	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/13 12:03
S35	4049	S34 not S32	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/13 12:04
S36	2512892	seal\$5 or encapsulat\$5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/13 12:04
S37	2022	S35 and S36	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/13 12:04
S38	1046	S37 and S27	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/13 12:07
S39	7072610	bond\$3 or attach\$4 or coupl\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/13 12:07
S40	1020	S38 and S39	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/13 12:10

S41	17239	S22 same (wafer or substrate) same S27	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/13 12:11
S42	178	S40 and S41	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/13 12:11
S43	2	("20020170175").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/13 17:34